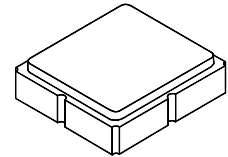


- SAW Filter for Digital Television
- Complies with Directive 2002/95/EC (RoHS)



SF2194E

**1220 MHz
SAW Filter**



SM3030-8

Maximum Rating

Rating	Value	Units
Input Power Level	0	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature	-30 to +85	°C
Storage Temperature in Tape and Reel	-40 to +85	°C
Maximum Soldering Profile, 5 cycles/10 seconds maximum	265	°C

Electrical Characteristics: +25°C ONLY

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_c			1220		MHz
Minimum Insertion Loss	IL_{MIN}			7.0	9.0	dB
3 dB Bandwidth	BW_3		0.500	0.750		MHz
Attenuation, Referenced to 0 dB						
300 to 1118 MHz			45	50		dB
1118 to 1146 MHz			45	50		
1146 to 1217 MHz			40	45		
1223 to 1300 MHz			40	45		
1300 to 2000 MHz			45	50		
Group Delay Ripple				50		ns _{P-P}
Source Impedance				50		W
Load Impedance				50		W

Case Style	SM3030-8 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization, Y=year, WW=week, S=shift, dot=pin 1 indicator	911, YWWS					
Standard Reel Quantity	Reel Size 7 Inch					500 Pieces/Reel
	Reel Size 13 Inch					3000 Pieces/Reel

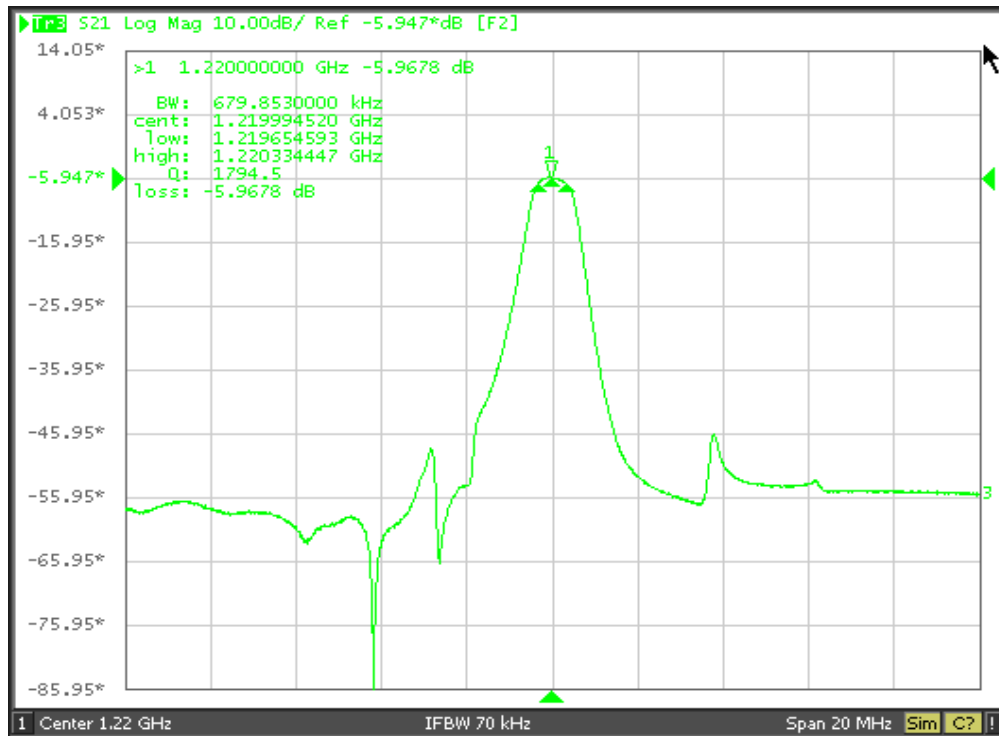
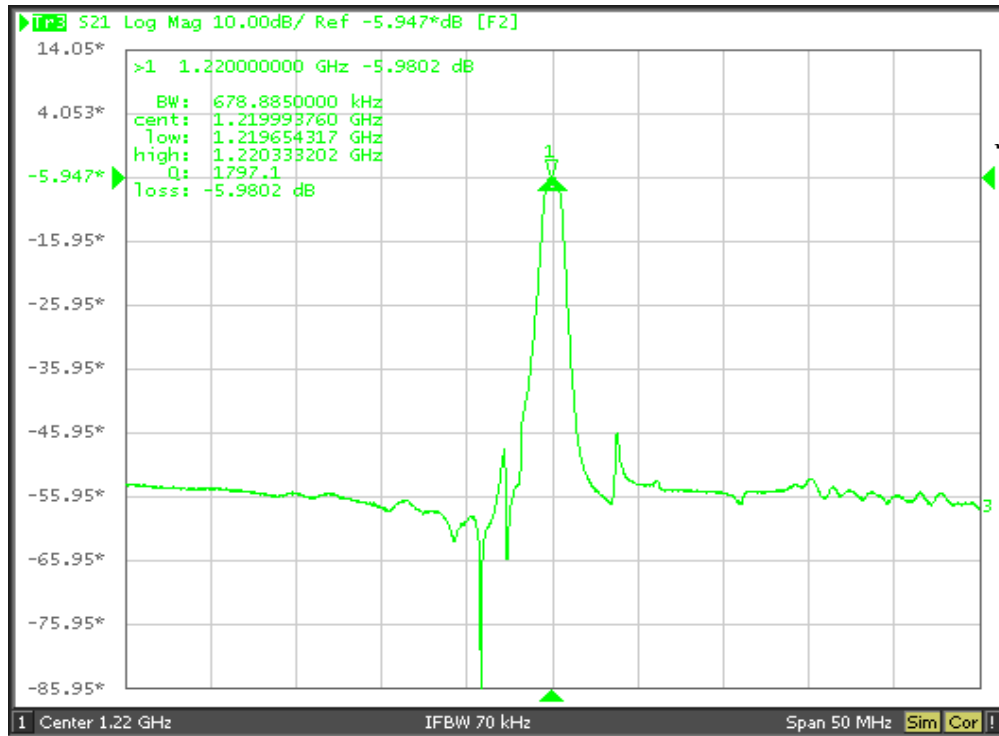


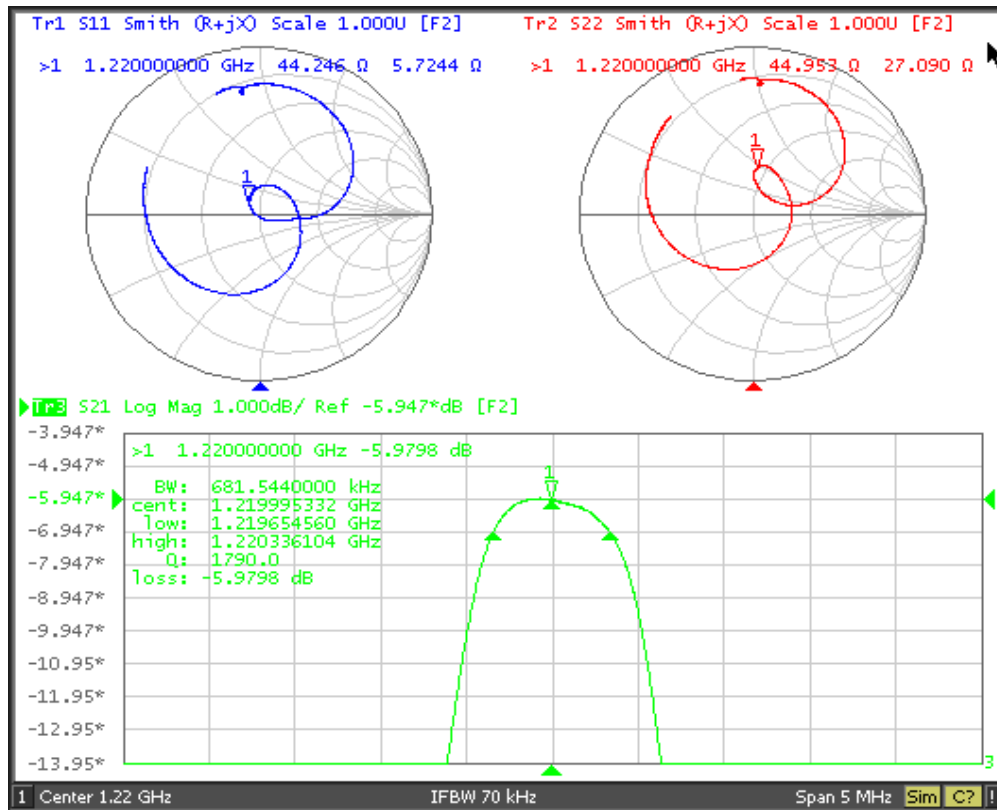
CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

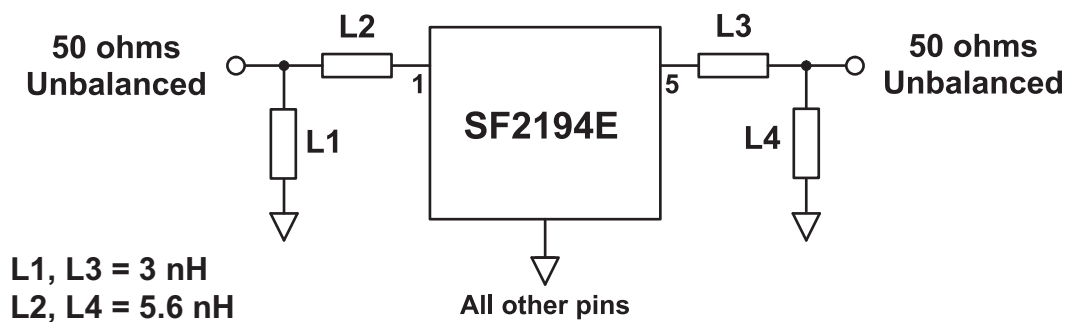
1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.

Frequency Response Plots

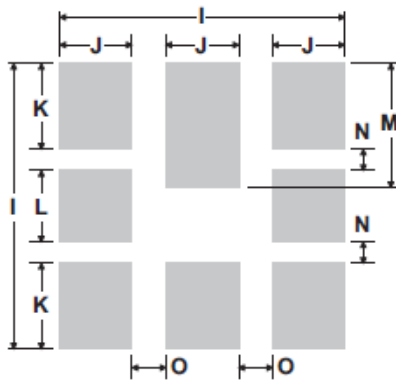
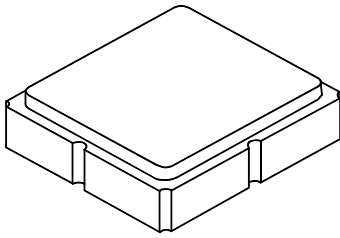




Matching Network Topology



8-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

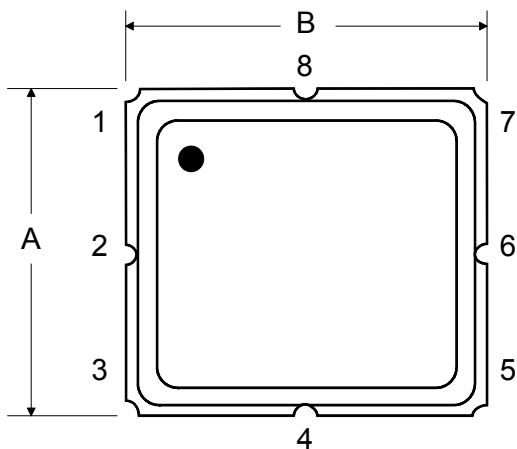
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.0	3.13	0.113	0.118	0.123
B	2.87	3.0	3.13	0.113	0.118	0.123
C	1.14	1.27	1.40	0.045	0.050	0.055
D	0.79	0.92	1.05	0.031	0.036	0.041
E	0.62	0.75	0.88	0.024	0.029	0.034
F	0.47	0.60	0.73	0.018	0.024	0.029
G	0.47	0.60	0.73	0.018	0.024	0.029
H	1.07	1.20	1.33	0.042	0.047	0.052
I		3.19			0.126	
J		0.81			0.032	
K		0.96			0.038	
L		0.81			0.032	
M		1.39			0.055	
N		0.23			0.009	
O		0.38			0.015	

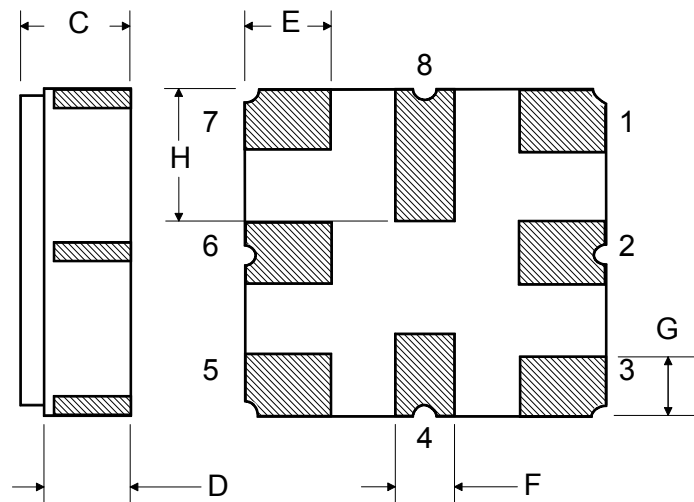
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic
Pb Free	

TOP VIEW



BOTTOM VIEW



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

